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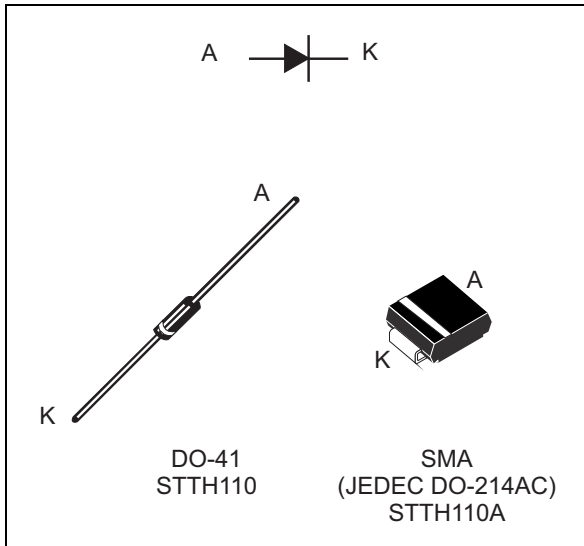
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



High voltage ultrafast rectifier

Datasheet - production data



Description

The STTH110, which is using ST ultrafast high voltage planar technology, is especially suited for free-wheeling, clamping, snubbing, demagnetization in power supplies and other power switching applications.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	1 A
V_{RRM}	1000 V
$T_{j(max)}$	175 °C
$V_F(max)$	1.42 V

Features

- Low forwarded voltage drop
- High reliability
- High surge current capability
- Soft switching for reduced EMI disturbances
- Planar technology

1 Characteristics

Table 2. Absolute ratings (limiting values at $T_j = 25\text{ °C}$, unless otherwise specified)

Symbol	Parameter		Value	Unit	
V_{RRM}	Repetitive peak reverse voltage		1000	V	
$V_{(RMS)}$	Voltage rms		700	V	
$I_{F(AV)}$	Average forward current	SMA	$T_L = 110\text{ °C } \delta = 0.5$	1	A
		DO-41	$T_L = 125\text{ °C } \delta = 0.5$	1	
I_{FSM}	Forward Surge current $t = 8.3\text{ ms}$	SMA		18	A
		DO-41		20	
T_{stg}	Storage temperature range		-50 to + 175	°C	
T_j	Maximum operating junction temperature		175	°C	

Table 3. Thermal resistance

Symbol	Parameter		Value	Unit
$R_{th(j-l)}$	Junction to lead	SMA	30	°C/W
		Lead length = 10 mm	DO-41	
$R_{th(j-a)}$	Junction to ambient	Lead length = 10 mm	DO-41	

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I_R	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = 1000\text{ V}$			10	μA
		$T_j = 125\text{ °C}$				50	
V_F	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 1\text{ A}$			1.7	V
		$T_j = 150\text{ °C}$			0.98	1.42	

To evaluate the conduction losses use the following equation:

$$P = 1.20 \times I_{F(AV)} + 0.225 I_{F(RMS)}^2$$

Table 5. Dynamic electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$T_j = 25\text{ °C}$	$I_F = 0.5\text{ A}$ $I_{rr} = 0.25\text{ A}$ $I_R = 1\text{ A}$			75	ns
t_{fr}	Forward recovery time	$T_j = 25\text{ °C}$	$I_F = 1\text{ A}$, $dI_F/dt = 50\text{ A/ms}$ $V_{FR} = 1.1 \times V_{Fmax}$			300	ns
V_{FP}	Forward recovery voltage						18

Figure 1. Conduction losses versus average current

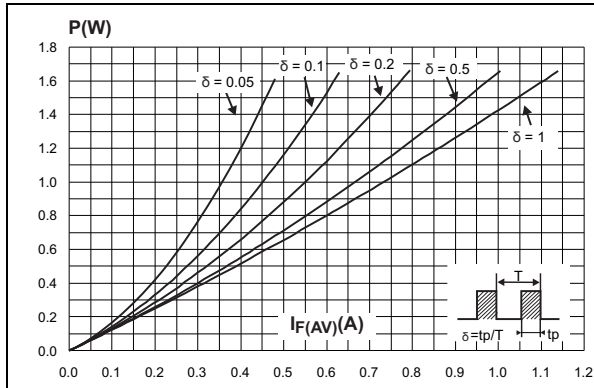


Figure 2. Forward voltage drop versus forward current (typical values)

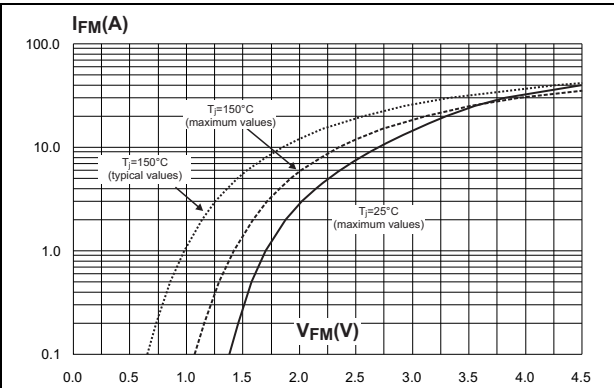


Figure 3. Relative variation of thermal impedance junction ambient versus pulse duration (DO-41)

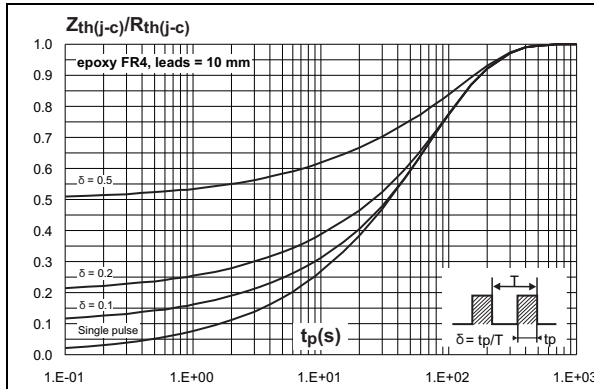


Figure 4. Relative variation of thermal impedance junction ambient versus pulse duration (SMA)

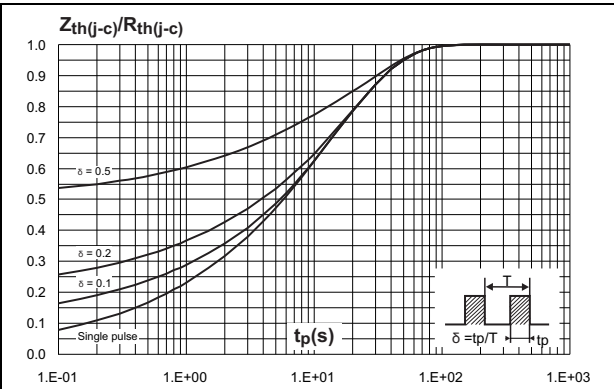


Figure 5. Thermal resistance junction to ambient versus copper surface under each lead (DO-41)

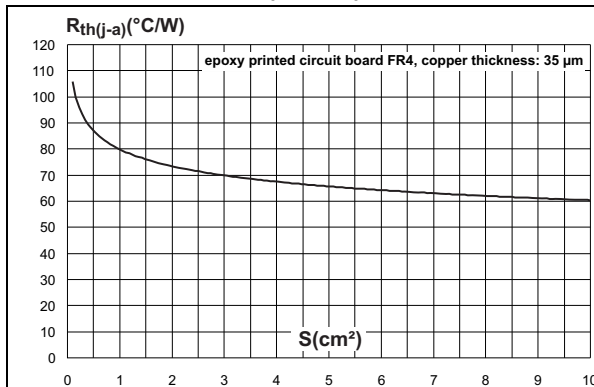
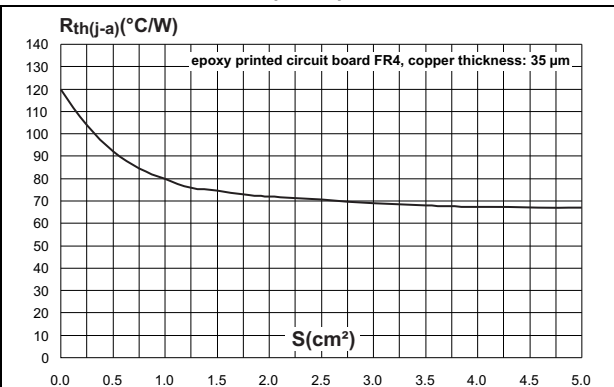


Figure 6. Thermal resistance junction to ambient versus copper surface under each lead (SMA)



2 Package information

- Epoxy meets UL94,V0
- Lead-free package
- Band indicates cathode
- Bending method (DO-41): see Application note AN1471

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Figure 7. SMA dimensions definitions

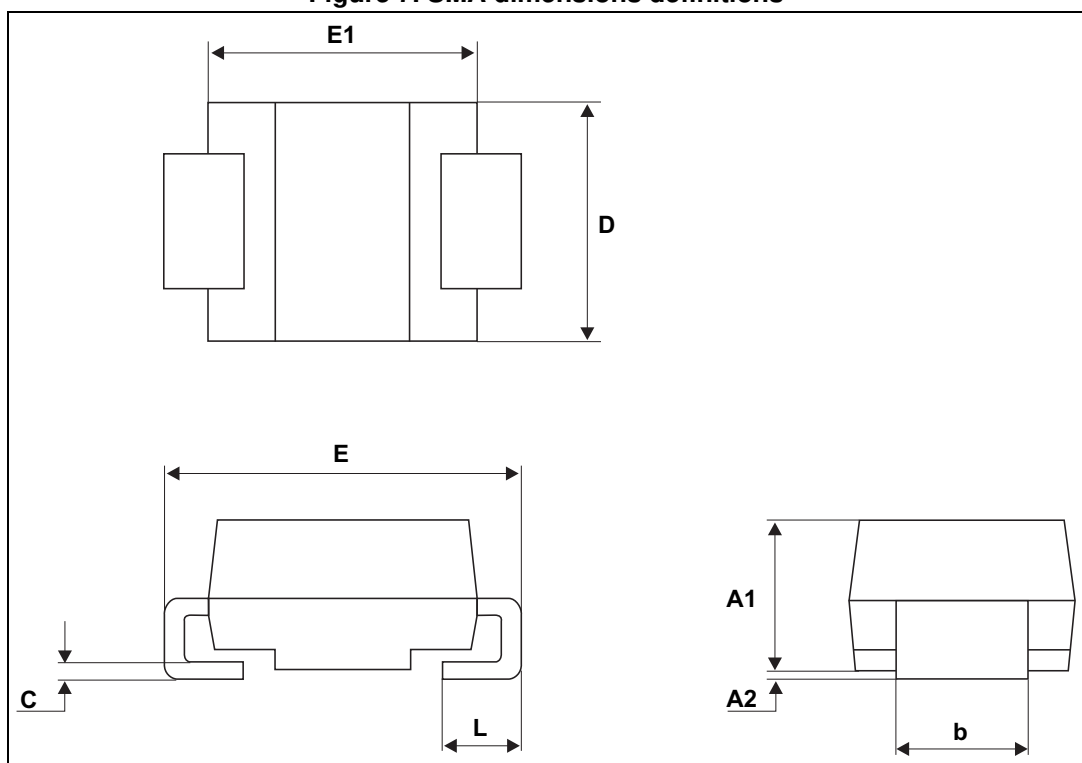


Table 6. SMA dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A1	1.90		2.45	0.075		0.094
A2	0.05		0.20	0.002		0.008
b	1.25		1.65	0.049		0.065
c	0.15		0.40	0.006		0.016
D	2.25		2.90	0.089		0.114
E	4.80		5.35	0.189		0.211
E1	3.95		4.60	0.156		0.181
L	0.75		1.50	0.030		0.059

Figure 8. SMA footprint, dimensions in mm (inches)

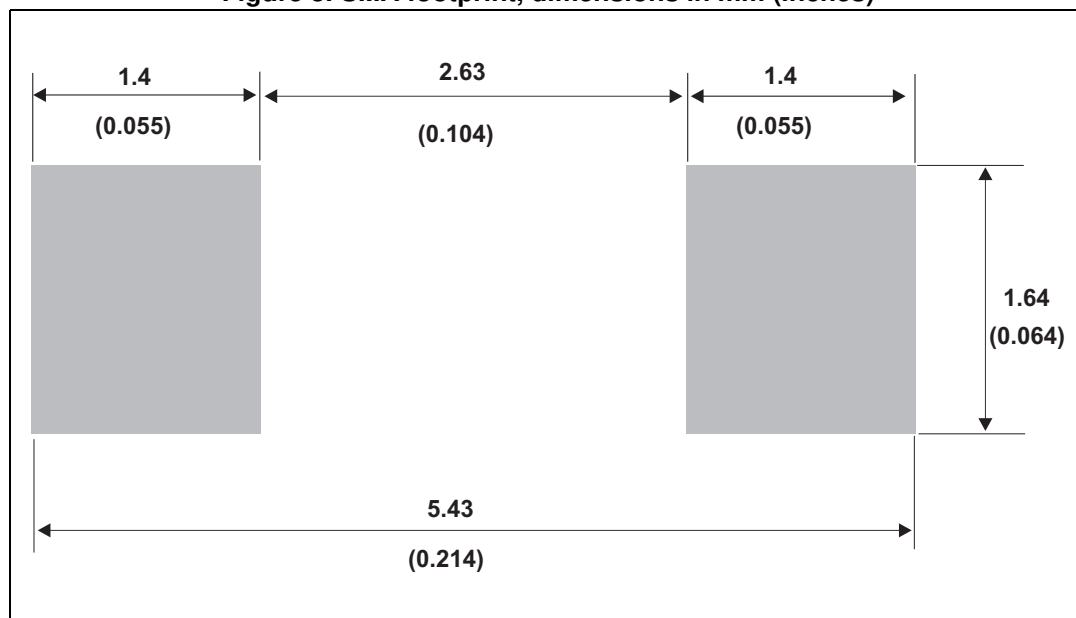


Figure 9. DO-41 (plastic) dimensions definitions

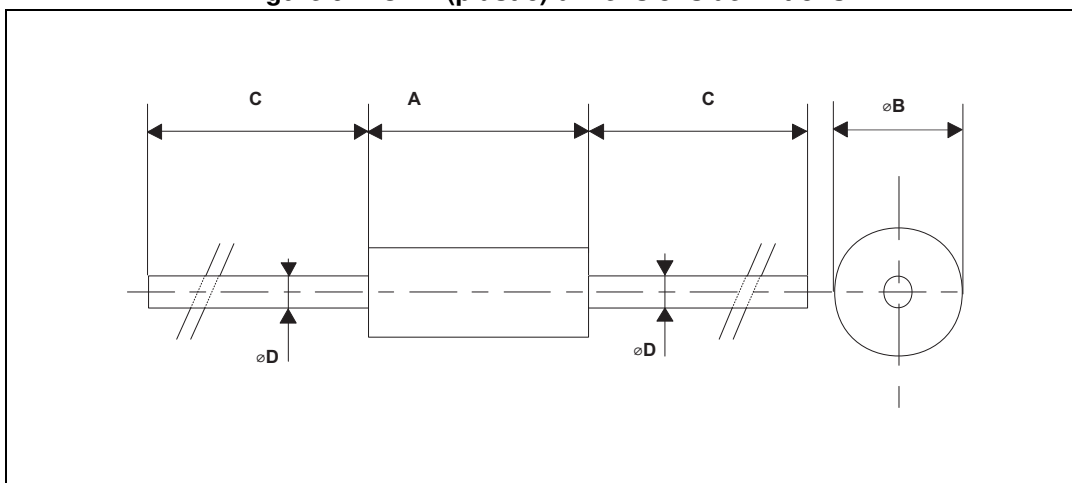


Table 7. DO-41 (plastic) dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.07		5.20	0.160		0.205
B	2.04		2.71	0.080		0.107
C	25.4			1		
D	0.71		0.86	0.028		0.034

3 Ordering information

Table 8. Ordering information

Order codes	Marking	Package	Weight	Base qty	Delivery mode
STTH110	STTH110	DO-41	0.34 g	2000	Ammopack
STTH110A	H10	SMA	0.068 g	5000	Tape and reel 13"
STTH110RL	STTH110	DO-41	0,34 g	5000	Tape and reel 13"

4 Revision history

Table 9. Document revision history

Date	Revision	Changes
Jan-2003	1	Initial release.
30-Sept-2009	2	Updated Table 8 .
20-Dec-2013	3	Updated Table 4 .

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